

L Number	Hits	Search Text	DB	Time stamp
-	582	(257/677).CCLS.	USPAT; US-PGPUB; EPO; JPO	2002/05/08 10:43
-	10	(257/\$.ccls. and (plastic adj tape)) and leadframe	USPAT; US-PGPUB; EPO; JPO	2002/05/07 15:09
-	598	(257/675).CCLS.	USPAT; US-PGPUB; EPO; JPO	2002/05/08 10:50
-	3	((257/675).CCLS.) and (mount adj pad)	USPAT; US-PGPUB; EPO; JPO	2002/05/07 15:23
-	131	((257/675).CCLS.) and tape	USPAT; US-PGPUB; EPO; JPO	2002/05/07 16:06
-	1594	(257/676).CCLS.	USPAT; US-PGPUB; EPO; JPO	2002/05/10 09:08
-	36	5157478.URPN.	USPAT	2002/05/08 08:21
-	393	((257/676).CCLS.) and tape	USPAT; US-PGPUB; EPO; JPO	2002/05/10 07:34
-	1594	(257/676).CCLS.	USPAT; US-PGPUB; EPO; JPO	2002/05/08 09:25
-	382	((257/676).CCLS.) and (die or chip or mount) near pad	USPAT; US-PGPUB; EPO; JPO	2002/05/08 09:34
-	115	((257/675).CCLS.) and (die or bond\$3 or mount) adj pad	USPAT; US-PGPUB; EPO; JPO	2002/05/08 11:12
-	79	semiconductor and package and downset and ((die or mount or chip or bond) adj pad)	USPAT; US-PGPUB; EPO; JPO	2002/05/08 13:56
-	2833	leadframe lead! adj frame near (chip die) adj (flag pad) near downset	USPAT; US-PGPUB; EPO; JPO	2002/05/08 14:03
-	16	(leadframe lead! adj frame) with ((chip die) adj (flag pad)) with downset	USPAT; US-PGPUB; EPO; JPO	2002/05/08 14:04
-	49	((257/676).CCLS.) and tape with ((die chip) adj (flag pad))	USPAT; US-PGPUB; EPO; JPO	2002/05/08 15:32
-	8	5854741.URPN.	USPAT	2002/05/08 16:23
-	5	("4691225"   "5473514"   "5583378"   "5614443"   "5671531").PN.	USPAT	2002/05/08 16:27
-	148	(361/750).CCLS.	USPAT; US-PGPUB; EPO; JPO	2002/05/10 09:11
-	7	((361/750).CCLS.) and (leadframe or lead adj frame)	USPAT; US-PGPUB; EPO; JPO	2002/05/09 07:58
-	383	(438/122).CCLS.	USPAT; US-PGPUB; EPO; JPO	2002/05/09 07:58
-	17	((438/122).CCLS.) and (die chip) adj (pad flag)	USPAT; US-PGPUB; EPO; JPO	2002/05/09 08:15
-	8	5854741.URPN.	USPAT	2002/05/09 08:04
-	79	((438/122).CCLS.) and tape	USPAT; US-PGPUB; EPO; JPO	2002/05/09 10:15
-	4	("5519936"   "5602059"   "6118178"   "6194778").PN.	USPAT	2002/05/09 08:21
-	23	5602059.URPN.	USPAT	2002/05/09 08:28

-	17	("4677528"   "4837184"   "5041396"   "5045921"   "5064706"   "5075760"   "5170328"   "5352633"   "5365655"   "5386339"   "5390079"   "5447886"   "5450283"   "5602059"   "5639695"   "5661086"   "5661088").PN.	USPAT	2002/05/09 09:02
-	11	5075760.URPN.	USPAT	2002/05/09 09:17
-	78	5045921.URPN.	USPAT	2002/05/09 09:38
-	657	(438/123).CCLS.	USPAT; US-PGPUB; EPO; JPO	2002/05/09 10:15
-	409	((438/126).CCLS.) ((438/123).CCLS.) and tape	USPAT; US-PGPUB; EPO; JPO	2002/05/09 10:16
-	189	((438/126).CCLS.) ((438/123).CCLS.) and tape) and TAB	USPAT; US-PGPUB; EPO; JPO	2002/05/09 10:17
-	5	((438/126).CCLS.) ((438/123).CCLS.) and tape) and carrier adj strip	USPAT; US-PGPUB; EPO; JPO	2002/05/09 10:17
-	488	(438/126).CCLS.	USPAT; US-PGPUB; EPO; JPO	2002/05/09 10:18
-	263	((438/126).CCLS.) ((438/123).CCLS.) and tape) and (leadframe lead adj frame)	USPAT; US-PGPUB; EPO; JPO	2002/05/09 10:20
-	35	((438/126).CCLS.) ((438/123).CCLS.) and tape) and (leadframe lead adj frame)) and (BGA or ball adj grid adj array)	USPAT; US-PGPUB; EPO; JPO	2002/05/09 10:20
-	220	(leadframe lead! adj frame with (chip die) adj (flag pad) with downset) and ((TAB base) adj (tape film)) or (carrier adj (strip tape)) or (flex\$4 adj circuitry))	USPAT; US-PGPUB; EPO; JPO	2002/05/09 12:41
-	32	257/\$.ccls. and (copper adj foil with nickel with gold)	USPAT; US-PGPUB; EPO; JPO	2002/05/09 14:31
-	41	((leadframe lead! adj frame with (chip die) adj (flag pad) with downset) and ((TAB base) adj (tape film)) or (carrier adj strip) or (flex adj circuitry)) ) and (BGA or (ball adj grid))	USPAT; US-PGPUB; EPO; JPO	2002/05/10 09:13